

## Performance Specification

Model	I <sub>hold</sub>	I <sub>trip</sub>	V <sub>max</sub>	I <sub>max</sub>	P <sub>d</sub>	Maximum Time		Resistance		
						To Trip		R <sub>i min.</sub>	R <sub>i max.</sub>	R <sub>1 max</sub>
	(A)	(A)	(Vrms)	(A)	(Sec)	(Ω)	(Ω)			
	(A)	(A)	(Vrms)	(A)	(Sec)	(Ω)	(Ω)	(Ω)		
JK600-050U	0.050	0.150	500	3.0	1.00	3.00	7.00	15.00	40.00	60.00
JK600-110U	0.110	0.220	600	3.0	1.00	3.00	8.00	6.00	16.00	24.00
JK600-150U	0.150	0.300	600	3.0	1.00	3.00	9.00	5.00	14.00	22.00
JK600-160U	0.160	0.320	600	3.0	1.00	3.00	10.00	4.00	12.00	18.00
JK600-200U	0.200	0.400	600	3.0	1.00	3.00	15.00	5.00	13.00	24.00

V<sub>max</sub> = Maximum operating voltage device can withstand without damage at rated current (I<sub>max</sub>).

I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>).

I<sub>hold</sub> = Hold Current. Maximum current device will not trip in 25°C still air.

I<sub>trip</sub> = Trip Current. Minimum current at which the device will always trip in 25°C still air.

P<sub>d</sub> = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

R<sub>i min/max</sub> = Minimum/Maximum device resistance prior to tripping at 25°C.



R<sub>1 max</sub> = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.

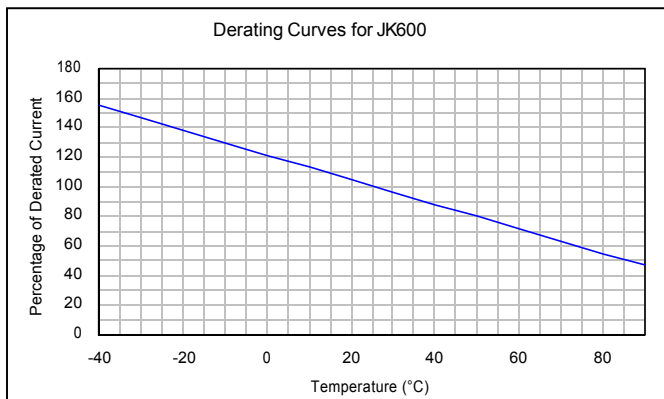
## Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-202, Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

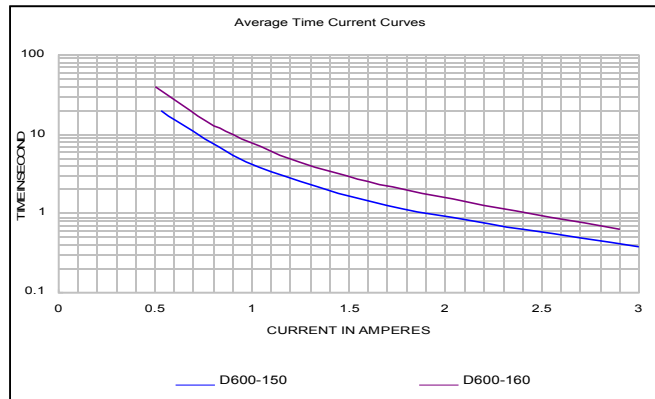
## Agency Approval and Environmental Compliance

Agency	File Number	Regulation	Standard
UL	pending		2002/95/EC
TUV	pending		EN14582

## Thermal Derating Curve



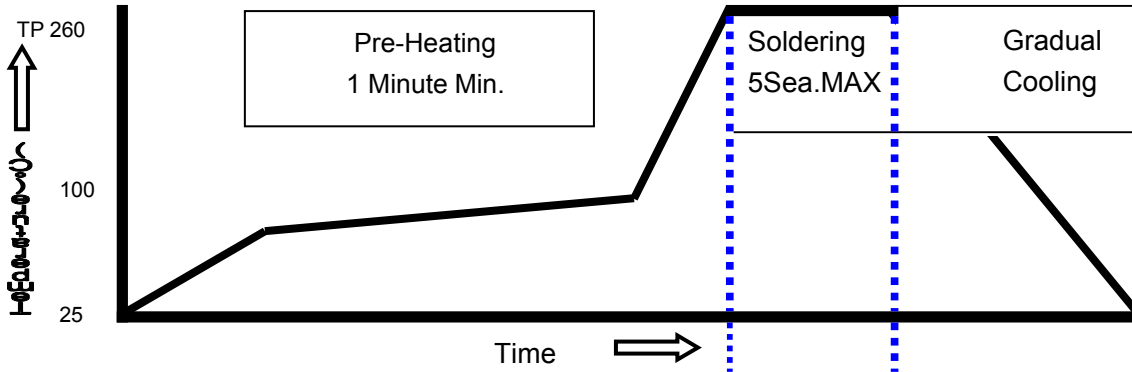
## Average Time-Current Curve



## Hold Versus Temperature

Model	Maximum ambient operating temperature ( $T_{mao}$ ) vs. hold current ( $I_{hold}$ )								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
JK600-150U	0.233	0.206	0.178	0.150	0.124	0.110	0.096	0.083	0.062
JK600-160U	0.249	0.219	0.190	0.160	0.132	0.117	0.103	0.088	0.066

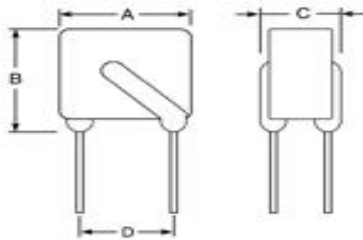
## Soldering Parameters



### WAVE SOLDERING INFORMATION

Pre-Heating Zone	Max. ramping rate should not exceed 4°C/Sec.
Soldering Zone	Max. solder temperature should not exceed 260°C
Cooling Zone	Cooling by natural convection in air.
© Specifications are subject to change without notice.	

## Physical Dimensions(mm.)



Model	A	B	C	D
	Max.	Max.	Max.	Typ.
JK600-050U	13.0	14.0	6.0	5.1
JK600-110U	14.0	14.0	6.0	5.1
JK600-150U	14.0	14.0	6.0	5.1
JK600-160U	14.0	14.0	6.0	5.1
JK600-200U	14.0	14.0	6.0	5.1

### PHYSICAL SPECIFICATIONS :

Materials :

JK600-: Tin-plated copper, 22AWG,  $\Phi 0.6\text{mm}$ (0.026 in). Lead

Solderability : MIL-STD-202, Method 208E

**Packaging Quantity: 200pcs/Bag Q'ty**